



Product Change Notification

108651 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 108651 - 00
Change Title: DQ35MP, PCN 108651-00, Product Material, SIO Supplier Change
Date of Publication: July 22, 2008

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Aug 21, 2008
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Description of Change to the Customer:

Winbond SIO chip now to be manufactured by Nuvoton. The die will be the same and there no be marking change on the part.

Customer Impact of Change and Recommended Action:

This change has been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel. This change is not expected to cause a change to the Microsoft* Windows* operating system.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change AA	Post Change AA
BLKDQ35MPE	888803	D82086-803	D82086-804
BOXDQ35MPE	888805	D82086-803	D82086-804
LADQ35MP	895064	D82086-803	D82086-804

PCN Revision History:

Date of Revision: July 22, 2008	Revision Number: 00	Reason: Originally Published PCN
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